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DEC 19 2002  
U.S. PATENT AND TRADEMARK OFFICE  
Case No.: AMKOR-045A  
Patent Appln.

#14  
Amend a  
DSmalls-logw  
1-8-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

|             |                         |   |            |                     |
|-------------|-------------------------|---|------------|---------------------|
| Applicant:  | Sung Sik Jang           | ) | Group No.: | 2826                |
| Serial No.: | 09/687,493              | ) | Examiner:  | Williams, Alexander |
| Filed:      | 10/13/2000              | ) |            |                     |
| For:        | SEMICONDUCTOR PACKAGE   | ) |            |                     |
|             | HAVING IMPROVED         | ) |            |                     |
|             | ADHESIVENESS AND GROUND | ) |            |                     |
|             | BONDING                 | ) |            |                     |

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AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON D.C. 20231

Dear Sir/Madam:

In response to the Office Action mailed October 15, 2002, in relation to the above-identified patent application, please amend the application as follows:

In the Specification:

Submitted herewith for the Examiner's consideration is a substitute specification attached as Exhibit A. A marked-up version of the substitute specification is attached as Exhibit B. The substitute specification has been modified in a manner believed to overcome the objection under 35 U.S.C. §132 presented in the Office Action by the Examiner in relation to the substitute specification submitted with Applicant's prior Amendment of July 10, 2002, as will be discussed in more detail below.